



20V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _A = +25°C
20V	$100 m\Omega @ V_{GS} = 4.5V$	1.8A
200	140mΩ @ $V_{GS} = 2.5V$	1.5A

Description

This new generation MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

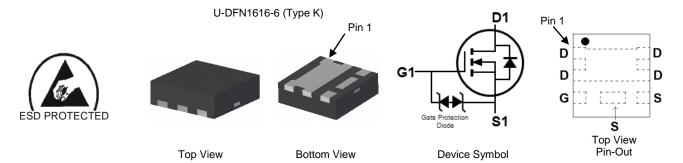
- Power Management Functions
- Load Switch

Features and Benefits

- Typical Off Board Profile of 0.6mm Ideally Suited for Thin Applications
- Low R_{DS(ON)} Minimizes Conduction Losses
- PCB Footprint of 2.56mm²
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: U-DFN1616-6
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Lead Free Plating (NiPdAu Finish over Copper Leadframe). (e4)
- Terminals: Solderable per MIL-STD-202, Method 208
- Weight: 0.003 grams (Approximate)



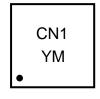
Ordering Information (Note 4)

- 3			
	Part Number	Case	Packaging
	DMN2120UFCL-7	U-DFN1616-6 (Type K)	3,000/Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



CN1 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: G = 2019) M = Month (ex: 9 = September)

Date Code Key

Year	2019	2	020	2021		2022	2023		2024	2025		2026
Code	G		Н	1		J	K		L	М		Ν
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings $(@T_A = +25^{\circ}C, \text{ unless otherwise specified.})$

Characteristic		Symbol	Value	Unit	
Drain-Source Voltage	V_{DSS}	20	V		
Gate-Source Voltage	V _{GSS}	±12	V		
Continuous Drain Current (Note 6) $V_{GS} = 4.5V$ Steady $T_A = +25^{\circ}C$ State $T_A = +70^{\circ}C$				1.8 1.4	А
Pulsed Drain Current (380µs Pulse, 1% Duty Cy	cle) (Note 7	I _{DM}	10	Α	
Maximum Continuous Body Diode Forward Curre	ent (Note 6)	Is	0.7	Α	

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	0.45	W
Thermal Resistance, Junction to Ambient @T _A = +25°C (Note 5)	$R_{ heta JA}$	270	°C/W
Power Dissipation (Note 6)	P _D	1.16	W
Thermal Resistance, Junction to Ambient @T _A = +25°C (Note 6)	$R_{ heta JA}$	108	°C/W
Operating and Storage Temperature Range	T _{J,} T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)	1					
Drain-Source Breakdown Voltage	BV _{DSS}	20	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_	_	1.0	μΑ	V _{DS} = 16V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}		_	±10	μΑ	$V_{GS} = \pm 12V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 8)			•		•	
Gate Threshold Voltage	V _{GS(TH)}	0.3	_	1.0	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$
		_	57	100		$V_{GS} = 4.5V, I_D = 3.6A$
Static Drain-Source On-Resistance	R _{DS(ON)}		69	140	mΩ	V _{GS} = 2.5V, I _D = 3.1A
		_	74	200		V _{GS} = 1.8V, I _D = 1A
Diode Forward Voltage	V _{SD}		0.7	1.2	V	V _{GS} = 0V, I _S = 1.6A
DYNAMIC CHARACTERISTICS (Note 9)			•		•	
Input Capacitance	C _{iss}	_	130	_	pF	
Output Capacitance	Coss	_	26	_	pF	$V_{DS} = 10V, V_{GS} = 0V,$ -f = 1.0MHz
Reverse Transfer Capacitance	C _{rss}		18	_	pF	1 = 1.0WII 12
Gate Resistance	Rg	_	2.7	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge (V _{GS} = 4.5V)	Qg	_	1.4	_	nC	
Total Gate Charge (V _{GS} = 10V)	Qg	_	2.8	_	nC	10/ 10/ 1
Gate-Source Charge	Q _{gs}	_	0.1	_	nC	$V_{DS} = 10V, I_{D} = 3.6A$
Gate-Drain Charge	Q_{gd}	_	0.5	_	nC	
Turn-On Delay Time	t _{D(ON)}	_	0.6	_	ns	
Turn-On Rise Time			2.7	_	ns	$V_{DD} = 10V, V_{GS} = 4.5V,$
Turn-Off Delay Time	t _{D(OFF)}		4.2	_	ns	$I_D = 1A$, $R_G = 6\Omega$, $R_L = 10\Omega$
Turn-Off Fall Time	t _F		1.7	_	ns	
Body Diode Reverse Recovery Time	t _{RR}		10	_	ns	I _F = 4A, dI/dt = 100A/µs
Body Diode Reverse Recovery Charge	Q _{RR}	_	1.0	_	nC	- 4Λ, αι/αι

Notes:

- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

 7. Repetitive rating, pulse width limited by junction temperature.
- 8. Short duration pulse test used to minimize self-heating effect.
- 9. Guaranteed by design. Not subject to product testing.



0.0

0

0.5

1

10.0 $V_{GS} = 3.0V$ $_{GS} = 4.0V$ $V_{GS} = 2.0V$ 8.0 ID, DRAIN CURRENT (A) $V_{GS} = 1.8V$ $V_{GS} = 4.5V$ 6.0 $V_{GS} = 1.5V$ 4.0 2.0

1.5 V_{DS}, DRAIN-SOURCE VOLTAGE (V) Figure 1. Typical Output Characteristic

2

 $V_{GS} = 1.2V$

2.5

3

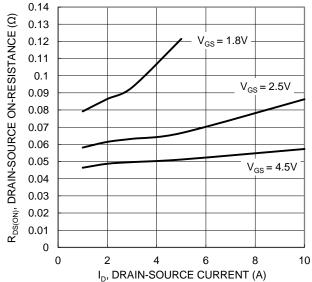


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

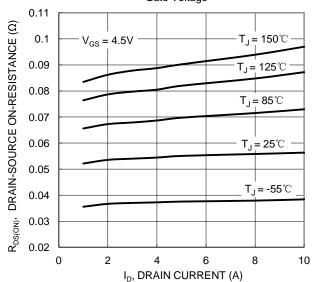


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

DMN2120UFCL

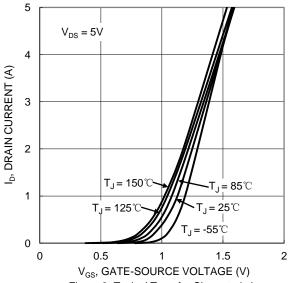
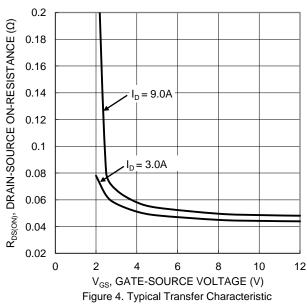


Figure 2. Typical Transfer Characteristic



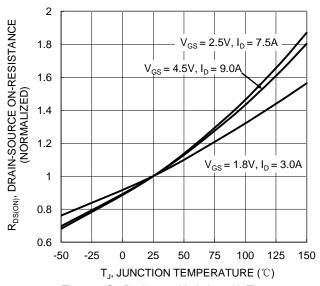


Figure 6. On-Resistance Variation with Temperature





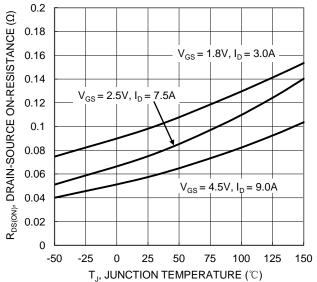


Figure 7. On-Resistance Variation with Temperature

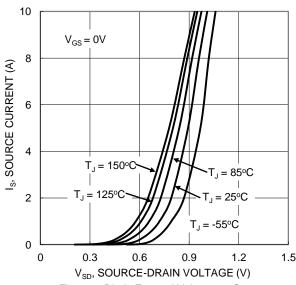
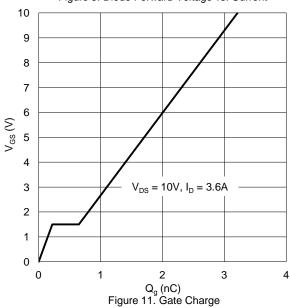


Figure 9. Diode Forward Voltage vs. Current



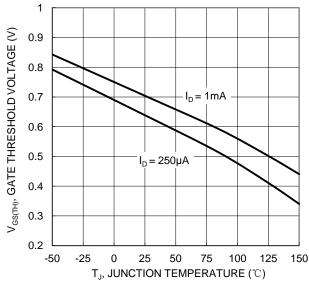


Figure 8. Gate Threshold Variation vs. Junction Temperature

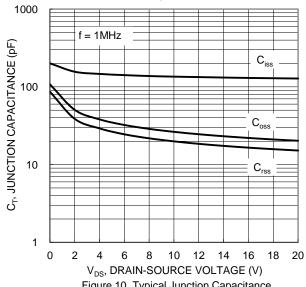
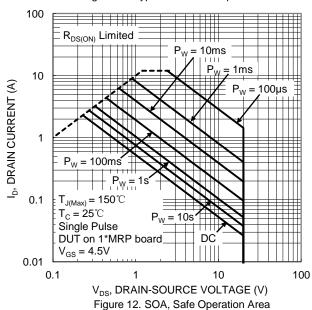


Figure 10. Typical Junction Capacitance





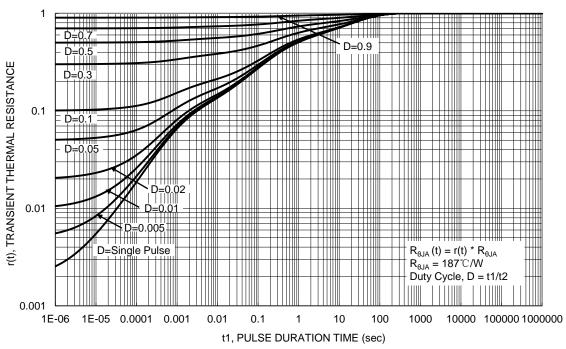


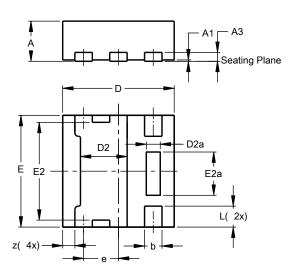
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN1616-6 (Type K)

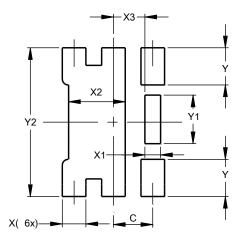


U-DFN1616-6								
(Type K)								
Dim	Min	Max	Тур					
Α	0.55	0.60	0.575					
A1	0.00	0.05	0.02					
A3	1		0.13					
b	0.20	0.30	0.25					
D	1.55	1.65	1.60					
D2	0.57	0.77	0.67					
D2a	0.10	0.30	0.20					
е	-		0.50					
Е	1.55	1.65	1.60					
E2	1.30	1.50	1.40					
E2a	0.52	0.72	0.62					
L	0.25	0.35	0.30					
z			0.175					
All Dimensions in mm								

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN1616-6 (Type K)



Dimensions	Value (in mm)
С	0.500
X	0.300
X1	0.200
X2	0.720
Х3	0.400
Υ	0.475
Y1	0.620
Y2	1.900



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